



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20181113000.1A**

**Qualification of CDAT as an additional Assembly/Test site for select devices in the QFN package**

**Change Notification / Sample Request**

**Date:** December 18, 2018

**To:** Newark/Farnell PCN

Dear Customer:

**Revision A** is to correct the CDAT Mount compound reference number in the description of change section.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services

**20181113000.1A**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TPS2552DRVR	null
TPS2552DRVT	null
TPS2553DRVT-1	null
BQ24308DSGT	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20181113000.1A		<b>PCN Date:</b>	Dec 18, 2018									
<b>Title:</b>	Qualification of CDAT as an additional Assembly/Test site for select devices in the QFN package												
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>		<b>Dept:</b>	Quality Services									
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Feb 16, 2019		<b>Estimated Sample Availability:</b>	Date Provided at Sample request									
<b>Change Type:</b>													
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site								
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material								
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process								
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site								
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials								
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process								
<b>PCN Details</b>													
<b>Description of Change:</b>													
<p><b>Revision A</b> is to correct the CDAT Mount compound reference number in the description of change section. Changes are indicted in yellow highlight below.</p> <p>Texas Instruments is pleased to announce the qualification of CDAT as additional Assembly and Test Site for Select Devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.</p> <table border="1" style="margin: 10px auto; width: 80%;"> <thead> <tr> <th></th> <th>UTL1</th> <th>TI Clark (DRV6 Only)</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mount compound</td> <td>SID#PZ0031</td> <td>4207768</td> <td>4207123 4208625</td> </tr> </tbody> </table> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>							UTL1	TI Clark (DRV6 Only)	CDAT	Mount compound	SID#PZ0031	4207768	4207123 4208625
	UTL1	TI Clark (DRV6 Only)	CDAT										
Mount compound	SID#PZ0031	4207768	4207123 4208625										
<b>Reason for Change:</b>													
Continuity of Supply													
<b>Anticipated impact on Material Declaration</b>													
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI Eco-Info website</a> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.										
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>													
None													

## Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
UTAC	NSE	THA	Bangkok
TI Clark	QAB	PHL	Angeles City, Pampanga
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>

Sample product shipping label (not actual product label)



## Product Affected:

BQ24045DSQR	BQ24308DSGT	TPS2553DRVR-1	UCC27201ADRMT
BQ24045DSQT	TPS2552DRVR	TPS2553DRVT-1	UCC27201DRMR
BQ24308DSGR	TPS2552DRVT	UCC27201ADRMR	UCC27201DRMT



TI Information  
Selective Disclosure

## Qualification Report

Approve Date 12-Nov-2018

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC27201ADRMR	QBS Package Reference: BQ24196RGER	QBS Package Reference: TPS2373-4	QBS Package Reference: TPS62140RGTR
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
FLAM	Flammability (UL 94V-0)	Method A/UL 94V-0	-	-	3/15/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-
HTOL	Life Test, 140C	480 Hours	-	-	1/77/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0	-
MSL	Thermal Path Integrity	Level 1-260C	3/36/0	-	-	-
MSL	Thermal Path Integrity	Level 2-260C	-	3/36/0	3/36/0	3/36/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/228/0

- QBS: Qual By Similarity  
- Qual Device UCC27201ADRMR is qualified at LEVEL1-260CG  
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
**Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>